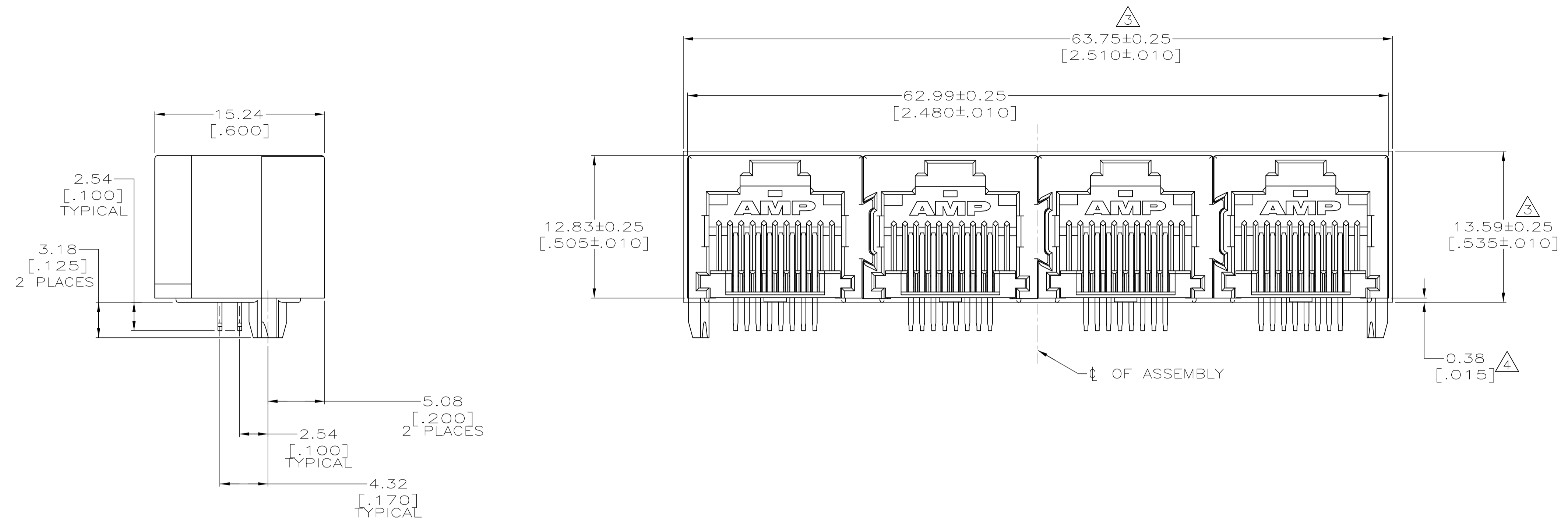
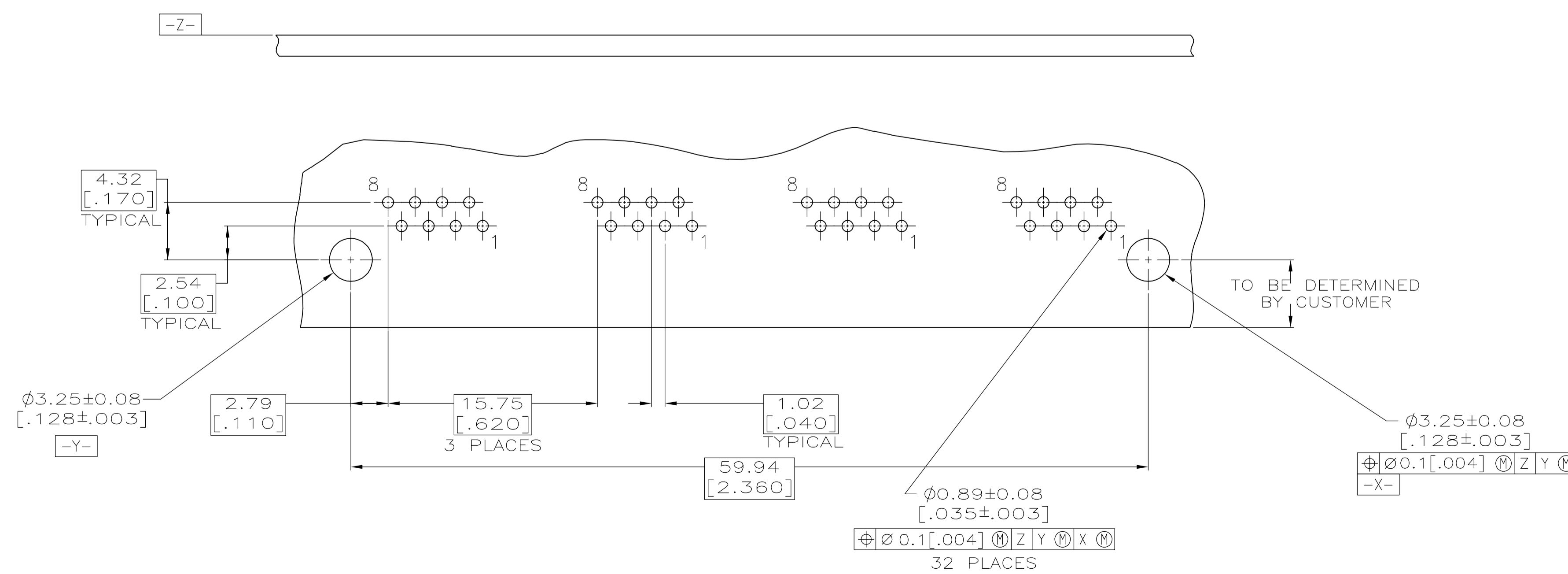


LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	OWN	APVD		
A		REV PER EC 0S11-0201-04	10JUN2005	JA	SF		



- △ MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; IR REFLOW SOLDERING PROCESS COMPATIBLE.
 TERMINALS - .36[.014] THICK PHOS BRONZE PLATED WITH 3.81μm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27μm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27μm [.000050] MINIMUM THICK NICKEL.
2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
- △ SUGGESTED CLEARANCE BETWEEN BOTTOM OF CONNECTOR AND BOTTOM PANEL OPENING.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 (COMPONENT SIDE)

5406528-1
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN J. ALCORTA - 10JUN2005		Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm[inches]		CHK J. WESTMAN - 10JUN2005		APD S. FLICKINGER - 10JUN2005	NAME
TOLERANCES UNLESS OTHERWISE SPECIFIED:		PRODUCT SPEC		108-1163-4	
0 PLC ± -		APPLICATION SPEC		114-2154	
1 PLC ± -		SIZE		A1	
2 PLC ± -		CAGE CODE		-	
3 PLC ± -		DRAWING NO		5406528	
4 PLC ± -		WEIGHT		-	
ANGLES ± -		CUSTOMER DRAWING		SCALE 4:1	
FINISH -		RESTRICTED TO		SHEET 1 OF 1	
		REV		A	